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501.43630X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): N. KAWANABE, et al
Serial No.: 10/807,249
Filed: March 24, 2004
For: A METHOD OF MANUFACTURING A SEMICONDUCTOR
DEVICE TO PROVIDE IMPROVED ADHESION BETWEEN
BONDING AND BALL PORTIONS OF ELECTRICAL
CONNECTORS (as amended)

Group:

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

May 5, 2004

Sir:

The following preliminary amendments and remarks are respectfully
submitted in connection with the above-identified application, as listed below and as
set forth on the following pages:

Substitute Specification and Marked Up Version of Original Specification;
Amendment of the Abstract; and
Remarks are included following the amendments.